RELIABILITY REPORT

FOR

MAX11614EEE+

PLASTIC ENCAPSULATED DEVICES

July 14, 2010

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
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Conclusion

The MAX11614EEE+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

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I. Device Description

A. General

The MAX11612-MAX11617 low-power, 12-bit, multichannel analog-to-digital converters (ADCs) feature internal track/hold (T/H), voltage reference, clock, and an I²C-compatible 2-wire serial interface. These devices operate from a single supply of 2.7V to 3.6V (MAX11613/MAX11615/MAX11617) or 4.5V to 5.5V (MAX11612/MAX11614/MAX11616) and require only 670µA at the maximum sampling rate of 94.4ksps. Supply current falls below 230µA for sampling rates under 46ksps. AutoShutdown(tm) powers down the devices between conversions, reducing supply current to less than 1µA at low throughput rates. The MAX11612/MAX11613 have 4 analog input channels each, the MAX11614/MAX11615 have 8 analog input channels each, while the MAX11616/MAX11617 have 12 analog input channels each. The fully differential analog inputs are software configurable for unipolar or bipolar, and single-ended or differential operation. The full-scale analog input range is determined by the internal reference or by an externally applied reference voltage ranging from 1V to VDD. The MAX11613/MAX11615/MAX11617 feature a 2.048V internal reference and the MAX11612/MAX11614/MAX11616 feature a 4.096V internal reference. The MAX11612/MAX11613 are available in an 8-pin µMAX® package. The MAX11614-MAX11617 are available in a 16-pin QSOP package. The MAX11612-MAX11617 are guaranteed over the extended temperature range (-40°C to +85°C). For pin-compatible 10-bit parts, refer to the MAX11606-MAX11611 data sheet. For pin-compatible 8-bit parts, refer to the MAX11600-MAX11605 data sheet.

II. Manufacturing Information

A. Description/Function:	2.7V to 3.6V and 4.5V to 5.5V, Low-Power, 4-/8-/12-Channel, 2-Wire Serial 12-Bit ADCs
B. Process:	C6Y
C. Number of Device Transistors:	12956
D. Fabrication Location:	Japan
E. Assembly Location:	Thailand
F. Date of Initial Production:	July 25, 2009

III. Packaging Information

A. Package Type:	16-pin QSOP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-3728
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	120°C/W
K. Single Layer Theta Jc:	37°C/W
L. Multi Layer Theta Ja:	103.7°C/W
M. Multi Layer Theta Jc:	37°C/W

IV. Die Information

A. Dimensions:	86 X 80 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.6 microns (as drawn)
F. Minimum Metal Spacing:	0.6 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 188 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 5.9 \times 10^{-9}$

$\lambda = 5.9$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim"s reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the C6Y Process results in a FIT Rate of 0.90 @ 25C and 15.55 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The AC31-4 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-100mA.

Table 1
Reliability Evaluation Test Results

MAX11614EEE+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	188	0
Moisture Testing (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data